

# SN54HC4002, SN74HC4002 DUAL 4-INPUT POSITIVE-NOR GATES

SCLS157

D2684, DECEMBER 1982—REVISED SEPTEMBER 1987

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

## description

These devices contain two independent 4-input positive NOR gates. They perform the Boolean functions:

$$Y = \overline{A + B + C + D} \text{ or } Y = \overline{A} \cdot \overline{B} \cdot \overline{C} \cdot \overline{D}$$

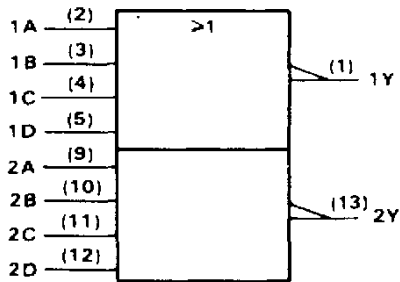
in positive logic.

The SN54HC4002 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74HC4002 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

FUNCTION TABLE

INPUTS				OUTPUT
A	B	C	D	Y
H	X	X	X	L
X	H	X	X	L
X	X	H	X	L
X	X	X	H	L
L	L	L	L	H

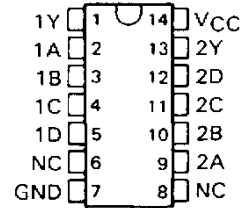
## logic symbol†



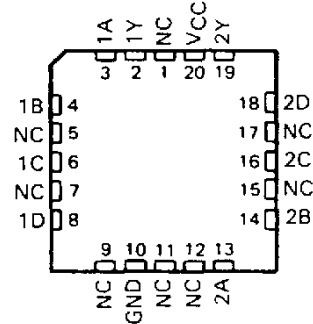
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

SN54HC4002 . . . J PACKAGE  
SN74HC4002 . . . D OR N PACKAGE  
(TOP VIEW)

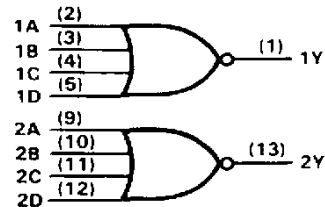


SN54HC4002 . . . FK PACKAGE  
(TOP VIEW)



NC—No internal connection

## logic diagram (positive logic)



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**SN54HC4002, SN74HC4002**  
**DUAL 4-INPUT POSITIVE-NOR GATES**

**absolute maximum ratings over operating free-air temperature range†**

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND pins .....	$\pm 50$ mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package .....	300°C
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package .....	260°C
Storage temperature range .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

**recommended operating conditions**

		SN54HC4002			SN74HC4002			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	2	5	6	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2$ V	1.5		1.5			V
		$V_{CC} = 4.5$ V	3.15		3.15			
		$V_{CC} = 6$ V	4.2		4.2			
$V_{IL}$	Low-level input voltage	$V_{CC} = 2$ V	0	0.3	0	0.3		V
		$V_{CC} = 4.5$ V	0	0.9	0	0.9		
		$V_{CC} = 6$ V	0	1.2	0	1.2		
$V_I$	Input voltage	0		$V_{CC}$	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	0		$V_{CC}$	V
$t_t$	Input transition (rise and fall) times	$V_{CC} = 2$ V	0	1000	0	1000		ns
		$V_{CC} = 4.5$ V	0	500	0	500		
		$V_{CC} = 6$ V	0	400	0	400		
$T_A$	Operating free-air temperature	-55		125	-40		85	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC4002		SN74HC4002		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$V_{OH}$	$V_I = V_{IH}$ or $V_{IL}$ , $I_{OH} = -20 \mu\text{A}$	2 V	1.9	1.998		1.9		1.9	V	
		4.5 V	4.4	4.499		4.4		4.4		
		6 V	5.9	5.999		5.9		5.9		
	4.5 V	3.98	4.30		3.7		3.84			
$V_{OL}$	$V_I = V_{IH}$ or $V_{IL}$ , $I_{OL} = 20 \mu\text{A}$	2 V		0.002	0.1		0.1		0.1	
		4.5 V		0.001	0.1		0.1		0.1	
		6 V		0.001	0.1		0.1		0.1	
	4.5 V		0.17	0.26		0.4		0.33		
$I_I$	$V_I = V_{CC}$ or 0	6 V		$\pm 0.1$	$\pm 100$		$\pm 1000$		$\pm 1000$	nA
		6 V			2		40		20	$\mu\text{A}$
$I_{CC}$	$V_I = V_{CC}$ or 0, $I_O = 0$	6 V								$\mu\text{A}$
$C_i$		2 to 6 V		3	10		10		10	pF



**SN54HC4002, SN74HC4002**  
**DUAL 4-INPUT POSITIVE-NOR GATES**

switching characteristics over recommended operating free-air temperature range (unless otherwise noted),  $C_L = 50 \text{ pF}$  (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC4002		SN74HC4002		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A thru D	Y	2 V		44	110		165		140	ns
			4.5 V		12	22		33		28	
			6 V		11	19		28		24	
t <sub>t</sub>		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

C <sub>pd</sub>	Power dissipation capacitance per gate	No load, T <sub>A</sub> = 25°C	25 pF typ
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Note 1: Load circuits and voltage waveforms are shown in Section 1.

  
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**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84044012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84044012A SNJ54HC 4002FK	
8404401CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8404401CA SNJ54HC4002J	
JM38510/65104BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65104BCA	
M38510/65104BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65104BCA	
SN54HC4002J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC4002J	
SN74HC4002N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-40 to 85		
SNJ54HC4002FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84044012A SNJ54HC 4002FK	
SNJ54HC4002J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8404401CA SNJ54HC4002J	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54HC4002, SN74HC4002 :**

- Catalog: [SN74HC4002](#)
- Military: [SN54HC4002](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002



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